

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	299367	(memory ic (integrated adj circuit) density high) with (card module)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:25
L2	181273	(semiconductor chip die dice ic component (integrated adj circuit)) with (middle center)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:23
L3	2449	1 same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:02
L4	739	(off offset offsetting offsetted) and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:23
L5	450	(substrate board pcb ((wiring printed circuit) with board)) and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:25
L6	288	(wire wiring) and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 13:58
L7	162	5 not 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 13:58
L8	654	(plurality stack stacking stacked stackable stack mount mounted mounting mountable) same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:23

L9	414	(dimm (dual with in with line with memory with module) substrate board pcb ((wiring printed circuit) with board)) and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:04
L10	7026684	(semiconductor chip die dice ic component (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:23
L11	879526	(plurality stack stacking stacked stackable stack mount mounted mounting mountable) with 10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:25
L12	266659	(off offset offsetting offsetted) with "11"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:24
L13	65822	(off offset offsetting offsetted) same 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:24
L14	20930	(off offset offsetting offsetted) with 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:24
L15	56186	(adjacent offset offsetting) with 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:24
L16	11411	(substrate board pcb ((wiring printed circuit) with board))same 15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:25

L17	313	16 same ((memory ic (integrated adj circuit) density high) with (card module))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:50
L18	2	"6404043".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:50
L19	2	"20010009505"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:51
L20	2	"20010010397"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:52
L21	2	"20020180060"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:52